

Appl. No. 10/730,834
Amdt. dated November 06, 2006
Reply to Office action of July 05, 2006

Amendments to the Specification:

Please substitute the title, as below:

CHIP STRUCTURE WITH ~~BUMPS AND TESTING PADS~~ HAVING BUMPS OR
5 WIREBONDED WIRES FORMED THEREOVER OR USED TO BE TESTED
THERE TO